

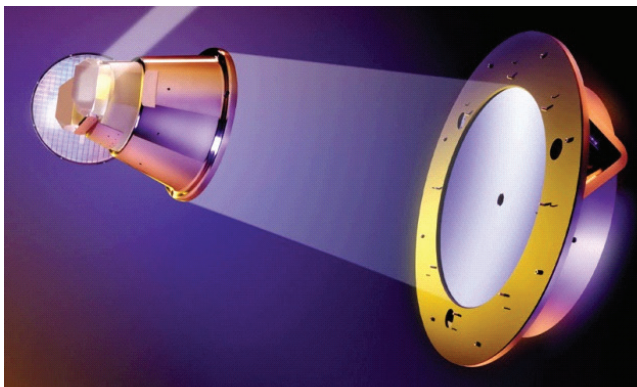
Advanced Packaging Lithography Leadership



AP 200/300 Stepper for Advanced Packaging, RF and MEMS

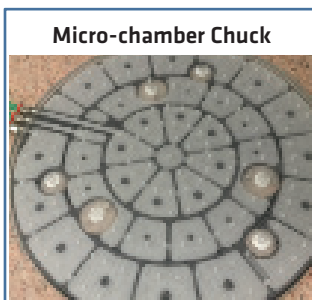
Superior Operational Flexibility for Multiple Applications

- > World-class HVM proven platform with full automation, selectable exposure wavelength and universal wafer size capability (6 & 8-in or 8 & 12-in wafers)
- > Adjustable Numerical Aperture projection optics for maximum DoF in thick and thin resists with 0.8 to 2.0 μm minimum resolution
- > Backside or buried layer IR alignment option for advanced processes including interposers and TSVs



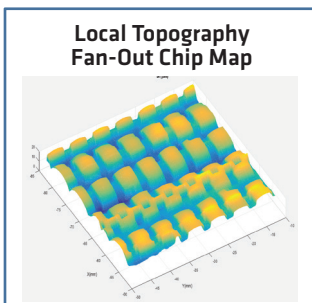
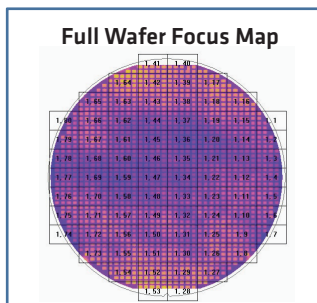
Key AP200/300 Stepper Advantages

- > Broadband Projection Lens (350 – 450nm)
- > Variable NA for 0.8 μ m to 2 μ m Minimum Resolution and Large Depth-of-Focus
- > Wafer Edge Processing for Electroplating Processes
- > Highest Economic Value with Lowest Production Risk



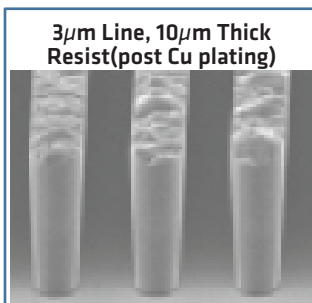
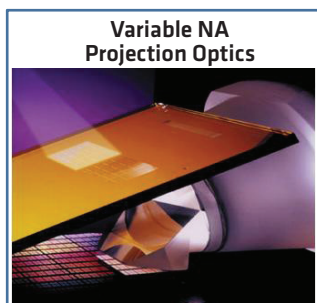
Warped Wafer Handling (± 10 mm)

- > Expands process window and yield for warped wafers by reducing chucked wafer flatness to below 1 μ m



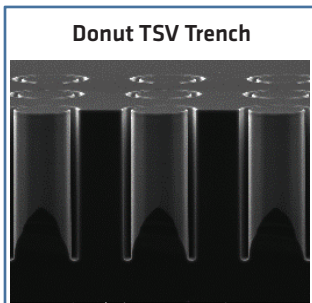
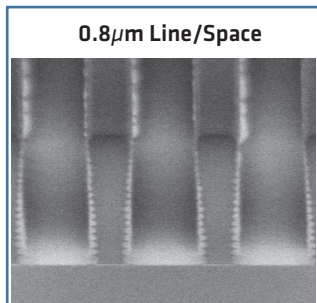
Full Wafer Mapping (Optical Focus)

- > Improves yield for smaller FOWLP feature sizes by providing full wafer topography map with ability to specify up to six locations per field for extremely accurate shot by shot focusing



Variable NA Projection Optics

- > Enables high aspect ratio lithography, large depth-of-focus and high wafer plane irradiance for thick resist applications



Sub 1 μ m Line/Space Resolution

- > Reduces cost of high connectivity packages and expands application space by significantly increasing overall I/O density

Find out more at
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